

Julien Sylvestre

List of Publications by Year in descending order

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2258059

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docs citations

7
times ranked

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citing authors

#	ARTICLE	IF	CITATIONS
1	Study of underfill corner cracks by the confocal-DIC and phantom-nodes methods. Microelectronics Reliability, 2022, 128, 114431.	1.7	3
2	Modeling of flip-chip underfill delamination and cracking with five input manufacturing variables. Microelectronics Reliability, 2022, 132, 114533.	1.7	3
3	Reservoir Computing in MEMS. Natural Computing Series, 2021, , 191-217.	2.2	5
4	In Situ Measurement Method for Temperature Profile Optimization During Thermocompression Bonding Process. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1929-1937.	2.5	2
5	Using Confocal Microscopy and Digital Image Correlation to Measure Local Strains Around a Chip Corner and a Crack Front. IEEE Transactions on Device and Materials Reliability, 2020, 20, 97-105.	2.0	8
6	Microfabricated Neuroaccelerometer: Integrating Sensing and Reservoir Computing in MEMS. Journal of Microelectromechanical Systems, 2020, 29, 338-347.	2.5	30
7	Modeling the Flip-Chip Wetting Process. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 2004-2017.	2.5	6